



A perspective view of a semiconductor device. The device consists of several layers labeled 3, 5, and 7 from bottom to top. On the left side, the layers are labeled N-, P+, and N+ from top to bottom. A central square pad is labeled 25. To its left is a rectangular feature labeled 21. Above it is another rectangular feature labeled 23. A small circular contact point is labeled G. A larger circular contact point is labeled S. A curved arrow points towards the right side of the device. A label D points to the bottom layer.